

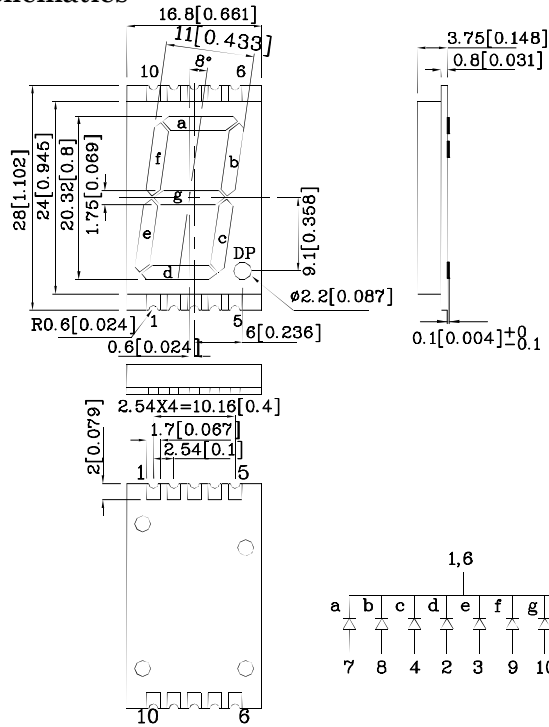
Features

- 0.8 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 200pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS compliant



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Package Schematics



Notes:

1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01)"unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.

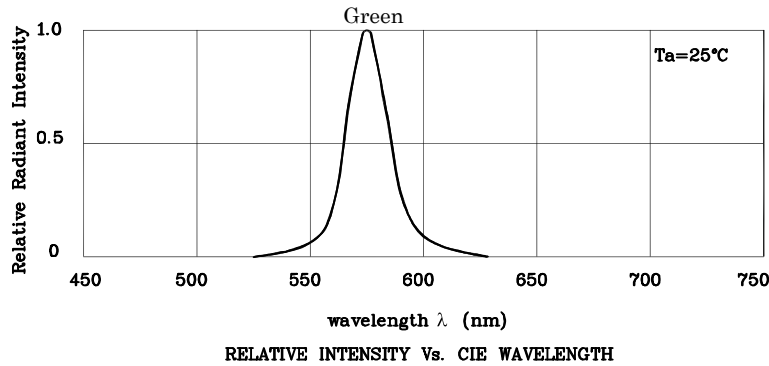
Absolute Maximum Ratings (T _A =25°C)		Green (AlGaInP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	150	mA
Power Dissipation	P _D	75	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

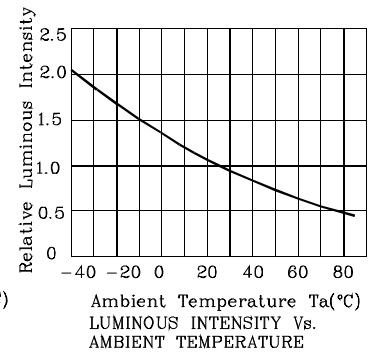
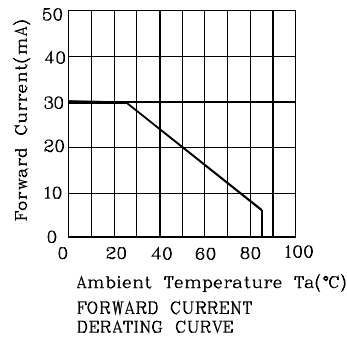
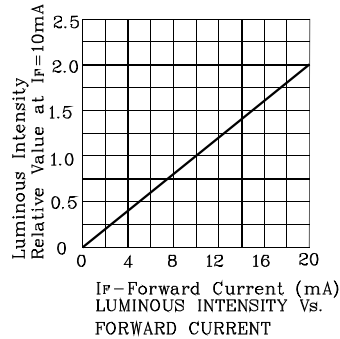
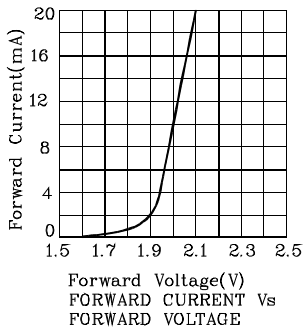
Operating Characteristics (T _A =25°C)		Green (AlGaInP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	2	V
Forward Voltage (Max.) (I _F =10mA)	V _F	2.5	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _P	574*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _D	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =10mA) ucd		Wavelength CIE127-2007* nm λ _P	Description
			min.	typ.		
XZFGV20C-A	Green	AlGaInP	9000 2200*	17990 5990*	574*	Common Cathode, Rt.Hand Decimal.

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

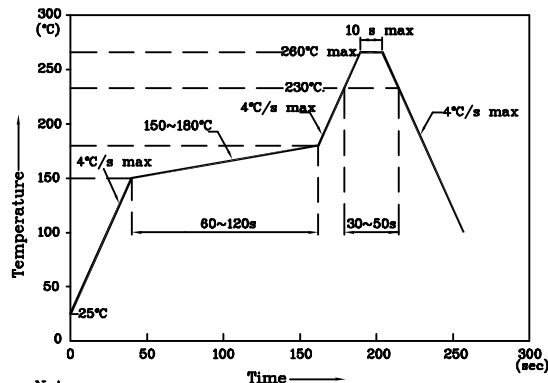


❖ Green



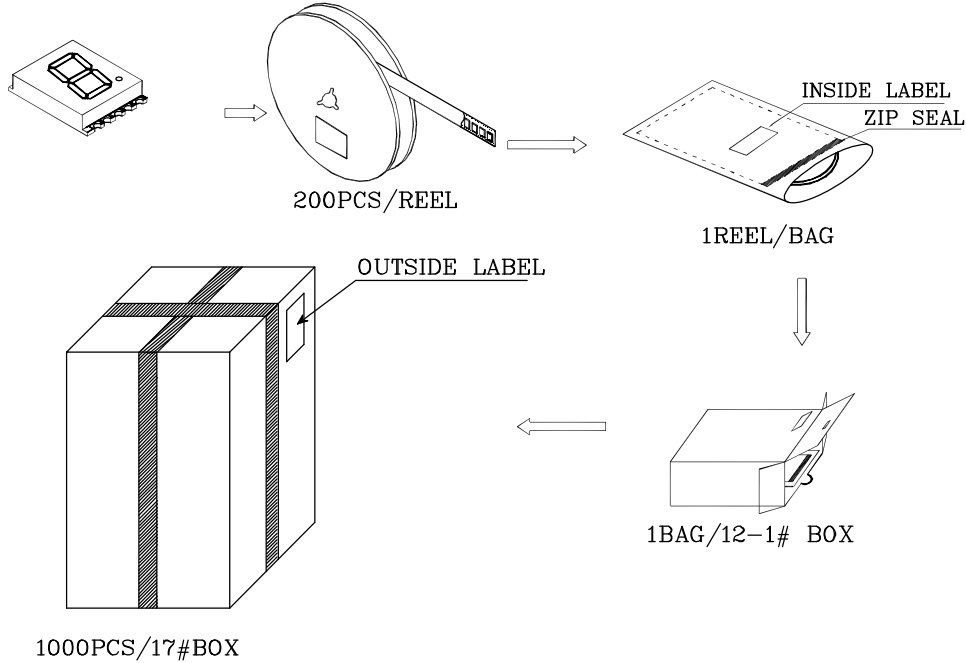
LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

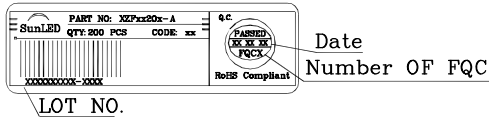


- Notes:
1. Maximum soldering temperature should not exceed 280°C
 2. Recommended reflow temperature: 145°C-260°C
 3. Do not put stress to the epoxy resin during high temperatures conditions

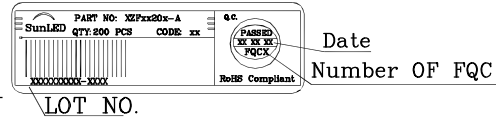
PACKING & LABEL SPECIFICATIONS



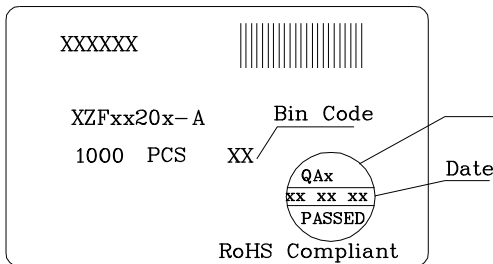
Inside Label On TAPE



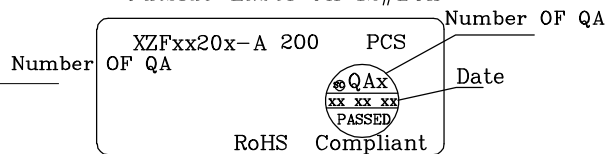
Outside Label On BAG



Outside Label On 19#Box



Outside Label On 12#Box



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